

General Description

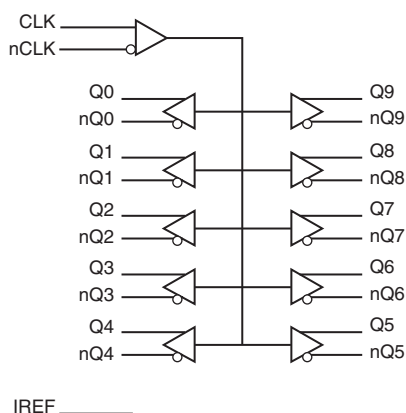
The ICS851010 is a 1-to-10 Differential HCSL Fanout Buffer. The ICS851010 is designed to translate any differential signal levels to differential HCSL output levels. An external reference resistor is used to set the value of the current supplied to an external load. The load resistor value is chosen to equal the value of the characteristic line impedance of 50Ω. The ICS851010 is characterized at an operating supply voltage of 3.3V.

The differential HCSL outputs, accurate crossover voltage and symmetric duty cycle makes the ICS851010 ideal for interfacing to PCI Express and FBDIMM applications.

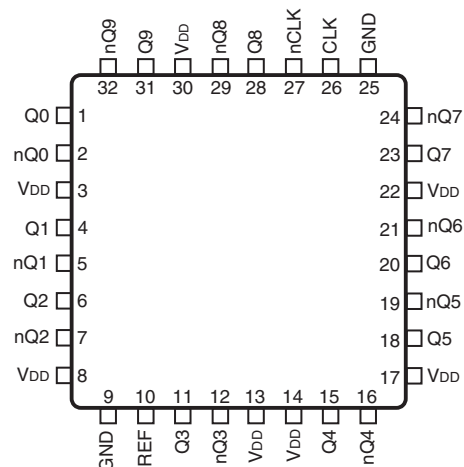
Features

- Ten differential HCSL outputs
- Translates any differential input signal (LVPECL, LVHSTL, LVDS, HCSL) to HCSL levels without external bias networks
- Maximum output frequency: 250MHz
- Output skew: 165ps (maximum)
- Part-to-part skew: 250ps (maximum)
- Output drift: 140ps (maximum)
- V_{OH} : 850mV (maximum)
- Full 3.3V supply voltage
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages
- 0°C to 70°C ambient operating temperature

Block Diagram



Pin Assignment



ICS851010

32-Lead LQFP

7mm x 7mm x 1.4mm package body

Y Package

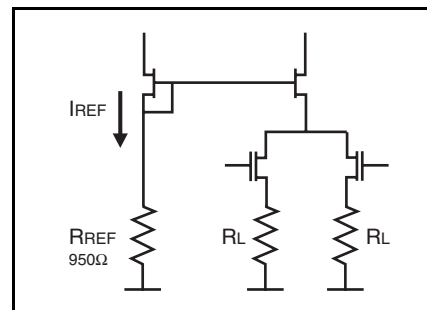
Top View

Table 1. Pin Descriptions

| Number | Name | Type | Description |
|-----------------------------|-----------------|--------|--|
| 1, 2 | Q0, nQ0 | Output | Differential output pair. Differential HCSL interface levels. |
| 3, 8, 13, 14, 17, 22, 30 | V _{DD} | Power | Positive supply pins. |
| 4, 5 | Q1, nQ1 | Output | Differential output pair. Differential HCSL interface levels. |
| 6, 7 | Q2, nQ2 | Output | Differential output pair. Differential HCSL interface levels. |
| 9, 25 | GND | Power | Power supply ground. |
| 10 | IREF | Input | Reference current input. Used to set the output current. Connect to 950Ω resistor to ground. |
| 11, 12 | Q3, nQ3 | Output | Differential output pair. Differential HCSL interface levels. |
| 15, 16 | Q4, nQ4 | Output | Differential output pair. Differential HCSL interface levels. |
| 18, 19 | Q5, nQ5 | Output | Differential output pair. Differential HCSL interface levels. |
| 20, 21 | Q6, nQ6 | Output | Differential output pair. Differential HCSL interface levels. |
| 23, 24 | Q7, nQ7 | Output | Differential output pair. Differential HCSL interface levels. |
| 26 | CLK | Input | Non-inverting differential input. |
| 27 | nCLK | Input | Inverting differential clock input. |
| 28, 29 | Q8, nQ8 | Output | Differential output pair. Differential HCSL interface levels. |
| 31, 32 | Q9, nQ9 | Output | Differential output pair. Differential HCSL interface levels. |

Output Driver Current

The ICS851010 outputs are HCSL differential current drive with the current being set with a resistor from I_{REF} to ground. For a *single load* and a 50Ω pc board trace, the drive current would typically be set with a R_{REF} of 950Ω which produces an I_{REF} of 1.16mA. The I_{REF} is multiplied by a current mirror to an output drive of 12*1.16mA or 13.90mA. See *Figure 1* for current mirror and output drive details.

**Figure 1. HCSL Current Mirror and Output Drive**

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

| Item | Rating |
|--|--------------------------|
| Supply Voltage, V_{DD} | 4.6V |
| Inputs, V_I | -0.5V to $V_{DD} + 0.5V$ |
| Outputs, I_O | -0.5V to $V_{DD} + 0.5V$ |
| Package Thermal Impedance, θ_{JA} | 65.7°C/W (0 mps) |
| Storage Temperature, T_{STG} | -65°C to 150°C |

DC Electrical Characteristics

Table 2A. Power Supply DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ to $70^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|----------|------------------------------|-----------------|---------|---------|---------|-------|
| V_{DD} | Core Supply Voltage | | 3.135 | 3.3 | 3.465 | V |
| I_{DD} | Power Supply Current; NOTE 1 | | | | 105 | mA |

NOTE 1: Measured using 200MHz input frequency.

Table 2B. Differential DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ to $70^\circ C$

| Symbol | Parameter | | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------|--------------------------------------|-----------|--------------------------------|-----------|---------|-----------------|---------|
| I_{IH} | Input High Current | CLK, nCLK | $V_{DD} = V_{IN} = 3.465V$ | | | 5 | μA |
| I_{IL} | Input Low Current | CLK, nCLK | $V_{DD} = 3.465V, V_{IN} = 0V$ | | | 5 | μA |
| V_{PP} | Peak-to-Peak Voltage; NOTE 1 | | | 0.15 | | 1.3 | V |
| V_{CMR} | Common Mode Input Voltage; NOTE 1, 2 | | | GND + 0.5 | | $V_{DD} - 0.85$ | V |

NOTE 1: V_{IL} should not be less than -0.3V.

NOTE 2: Common mode input voltage is defined as V_{IH} .

AC Electrical Characteristics

Table 3. HCSL AC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ to $70^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|--------------------|--|--|---------|---------|---------|-------|
| f_{MAX} | Output Frequency | | | | 250 | MHz |
| t_{PD} | Propagation Delay; NOTE 1 | Measured on at V_{OX} | 1.5 | | 2.75 | ns |
| $t_{sk(o)}$ | Output Skew; NOTE 2, 3 | Measured on at V_{OX} | | | 165 | ps |
| $t_{sk(pp)}$ | Part-to-Part Skew; NOTE 3, 4 | | | | 250 | ps |
| f_{jit} | Buffer Additive Phase Jitter, RMS | CLK = 200MHz, Integration Range: 12kHz – 30MHz | | 0.24 | | ps |
| $t_{sk(drift)}$ | Output Drift; NOTE 5 | | | | 140 | ps |
| V_{MAX} | Absolute Max Output Voltage; NOTE 6 | $f \leq 150MHz$ | 500 | | 850 | mV |
| V_{MIN} | Absolute Min Output Voltage; NOTE 6 | $f \leq 150MHz$ | -150 | | 150 | mV |
| V_{CROSS} | Absolute Crossing Voltage; NOTE 7, 8, 9 | | 250 | | 550 | mV |
| ΔV_{CROSS} | Total Variation of V_{CROSS} over all edges; NOTE 7, 8, 10 | | | | 140 | mV |
| t_R / t_F | Rise/Fall Edge Rate; NOTE 11, 12 | | 0.6 | | 4.0 | V/ns |
| odc | Output Duty Cycle; NOTE 13 | | 47 | | 53 | % |

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE: Current adjust set for $V_{OH} = 0.7V$. Measurements refer to PCIEX outputs only.

NOTE: Characterized using an R_{REF} value of 950Ω resistor.

NOTE 1: Measured from the differential input cross point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the differential output cross point.

NOTE 3: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltage, same frequency, same temperature and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross point.

NOTE 5: Output Drift is measured as the change in the time placement of the differential cross point for each output on a given device due to a change in temperature and supply voltage. Measured at the differential cross point.

NOTE 6: Measurement using $R_{REF} = 950\Omega$, $R_{LOAD} = 50\Omega$.

NOTE 7: Measurement taken from single-ended waveform.

NOTE 8: Measured at crossing point where the instantaneous voltage value of the rising edge of Q_x equals the falling edge of nQ_x .

See Parameter Measurement Information Section.

NOTE 9: Refers to the total variation from the lowest crossing point to the highest, regardless of which edge is crossing. Refers to all crossing points for this measurement. See Parameter Measurement Information Section.

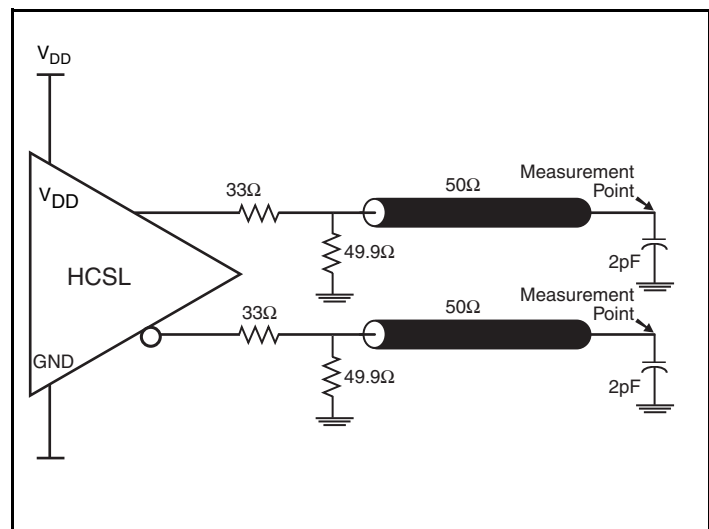
NOTE 10: Defined as the total variation of all crossing voltage of rising Q_x and falling nQ_x . This is the maximum allowed variance in the V_{CROSS} for any particular system. See Parameter Measurement Information Section.

NOTE 11: Measurement taken from differential waveform.

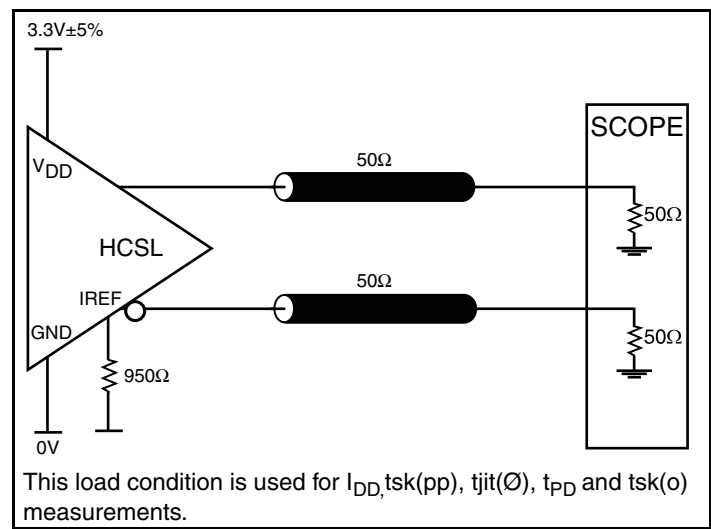
NOTE 12: Measurement from -150mV to +150mV on the differential waveform (derived from Q_x minus nQ_x). The signal must be monotonic through the measurement region for rise and fall time. The 300mV measurement window is centered on the differential zero crossing.

NOTE 13: Assuming 50% input duty cycle. Data taken at $f \leq 200MHz$, unless otherwise specified.

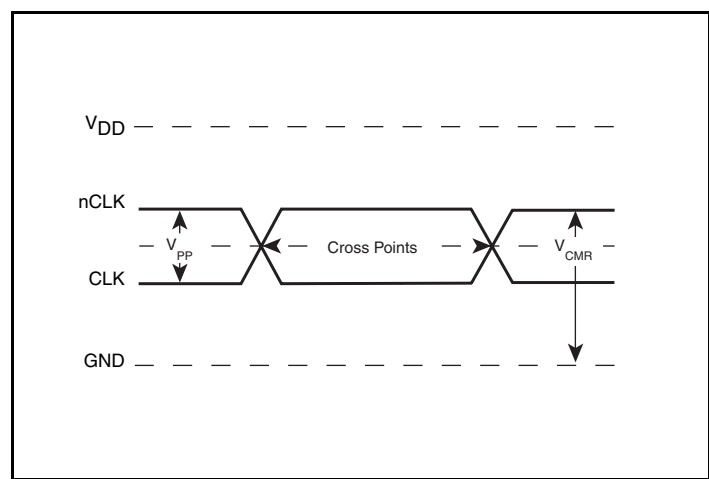
Parameter Measurement Information



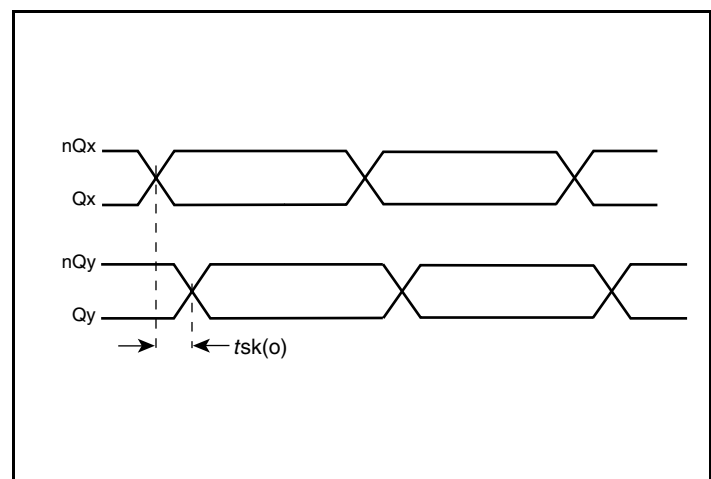
HCSSL Output Load AC Test Circuit



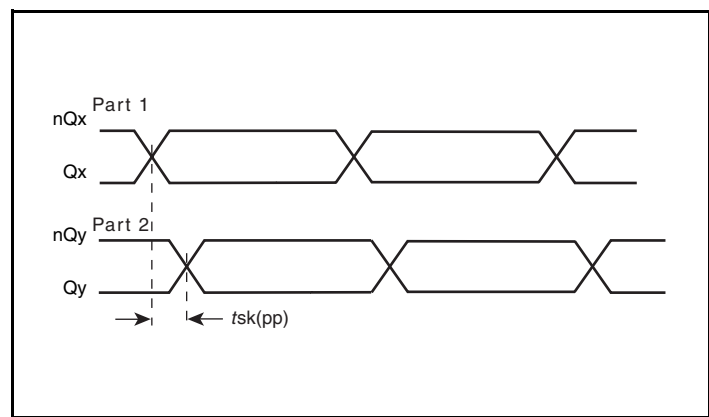
HCSSL Output Load AC Test Circuit



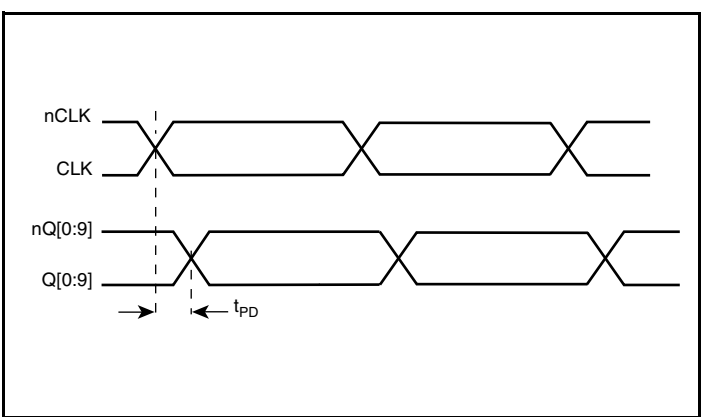
Differential Input Levels



Output Skew

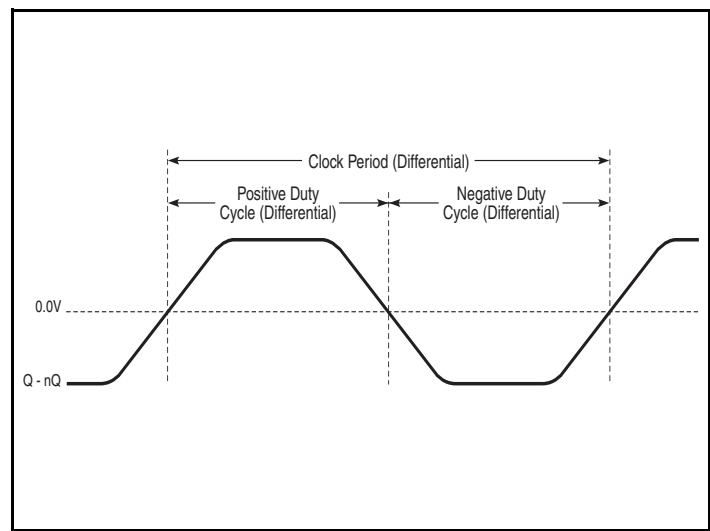


Part-to-Part Skew

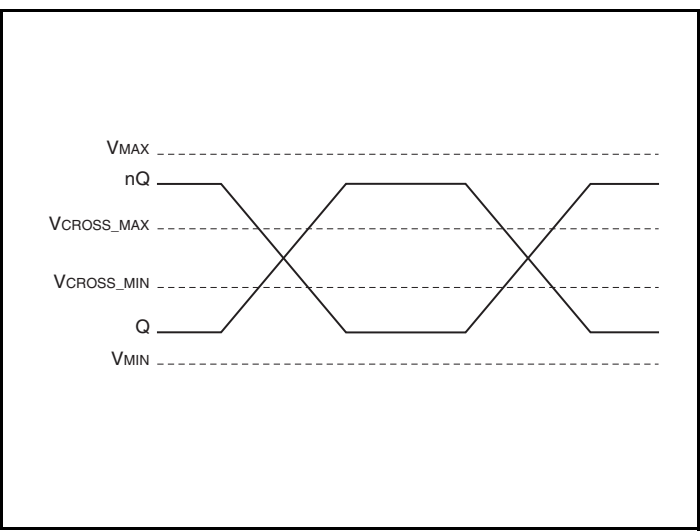


Propagation Delay

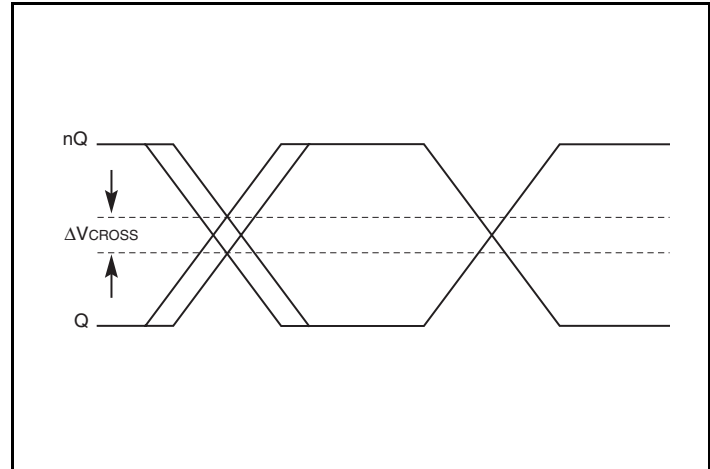
Parameter Measurement Information, continued



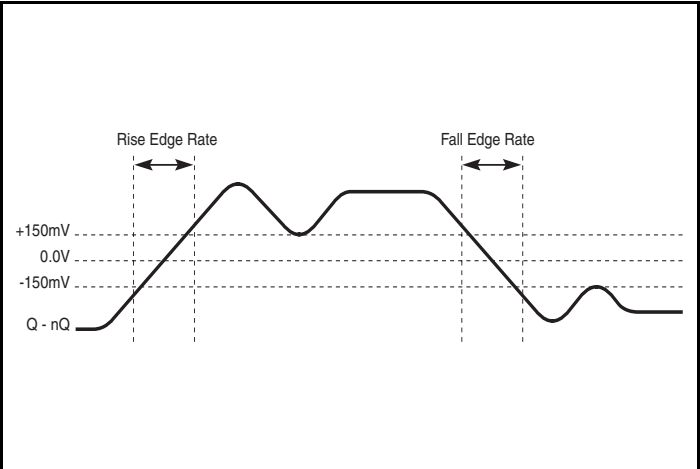
Differential Measurement Points for Duty Cycle/Period



Single-ended Measurement Points for Absolute Cross Point and Swing



Single-ended Measurement Points for Delta Cross Point



Differential Measurement Points for Rise/Fall Edge Rate

Applications Information

Recommendations for Unused Output Pins

Outputs:

Differential Outputs

All unused differential outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

Wiring the Differential Input to Accept Single-Ended Levels

Figure 2 shows how a differential input can be wired to accept single ended levels. The reference voltage $V_{REF} = V_{DD}/2$ is generated by the bias resistors R1 and R2. The bypass capacitor (C1) is used to help filter noise on the DC bias. This bias circuit should be located as close to the input pin as possible. The ratio of R1 and R2 might need to be adjusted to position the V_{REF} in the center of the input voltage swing. For example, if the input clock swing is 2.5V and $V_{DD} = 3.3V$, R1 and R2 value should be adjusted to set V_{REF} at 1.25V. The values below are for when both the single ended swing and V_{DD} are at the same voltage. This configuration requires that the sum of the output impedance of the driver (R_o) and the series resistance (R_s) equals the transmission line impedance. In addition, matched termination at the input will attenuate the signal in half. This can be done in one of two ways. First, R3 and R4 in parallel should equal the transmission

line impedance. For most 50Ω applications, R3 and R4 can be 100Ω. The values of the resistors can be increased to reduce the loading for slower and weaker LVCMOS driver. When using single-ended signaling, the noise rejection benefits of differential signaling are reduced. Even though the differential input can handle full rail LVCMOS signaling, it is recommended that the amplitude be reduced. The datasheet specifies a lower differential amplitude, however this only applies to differential signals. For single-ended applications, the swing can be larger, however V_{IL} cannot be less than -0.3V and V_{IH} cannot be more than $V_{DD} + 0.3V$. Though some of the recommended components might not be used, the pads should be placed in the layout. They can be utilized for debugging purposes. The datasheet specifications are characterized and guaranteed by using a differential signal.

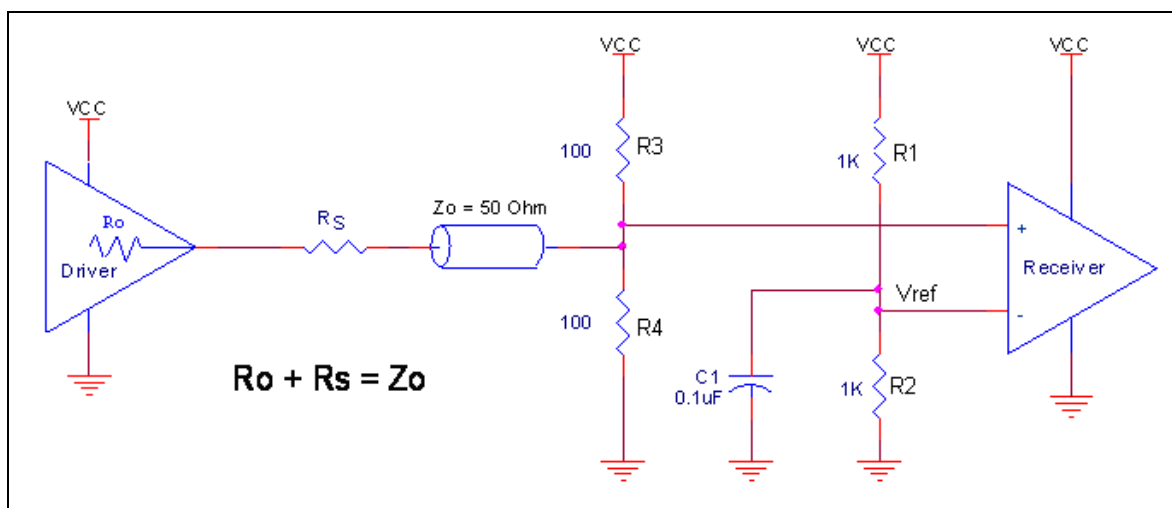


Figure 2. Recommended Schematic for Wiring a Differential Input to Accept Single-ended Levels

Differential Clock Input Interface

The CLK/nCLK accepts HCSL, LVDS, LVPECL and SSTL and other differential signals. Both differential signals must meet the V_{PP} and V_{CMR} input requirements. *Figures 3A to 3F* show interface examples for the CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult

with the vendor of the driver component to confirm the driver termination requirements. For example in Figure 3A, the input termination applies for IDT open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

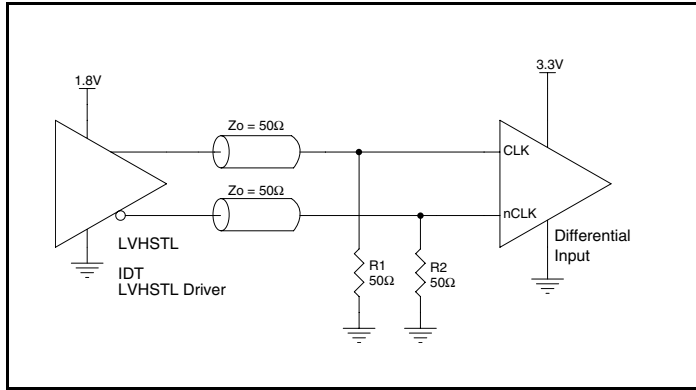


Figure 3A. CLK/nCLK Input Driven by an IDT Open Emitter LVHSTL Driver

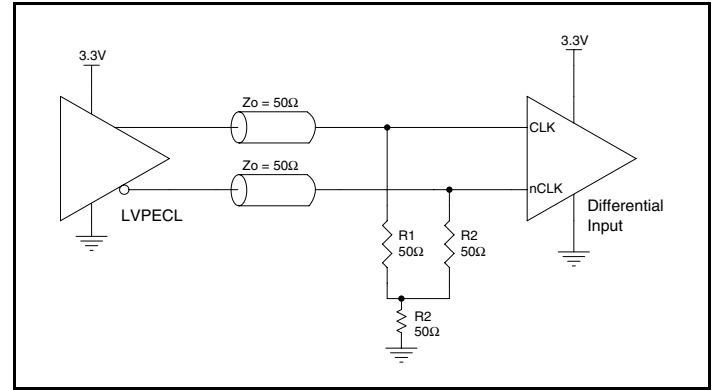


Figure 3B. CLK/nCLK Input Driven by a 3.3V LVPECL Driver

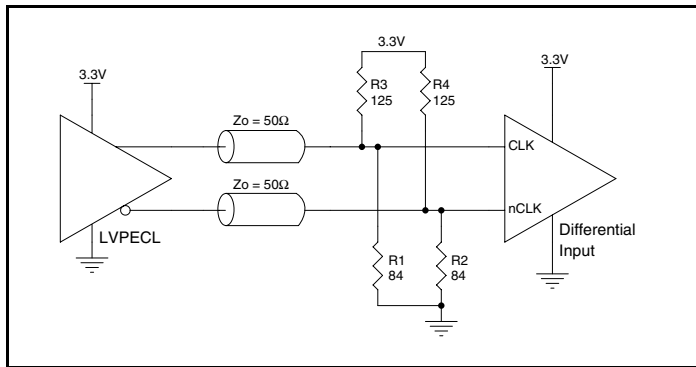


Figure 3C. CLK/nCLK Input Driven by a 3.3V LVPECL Driver

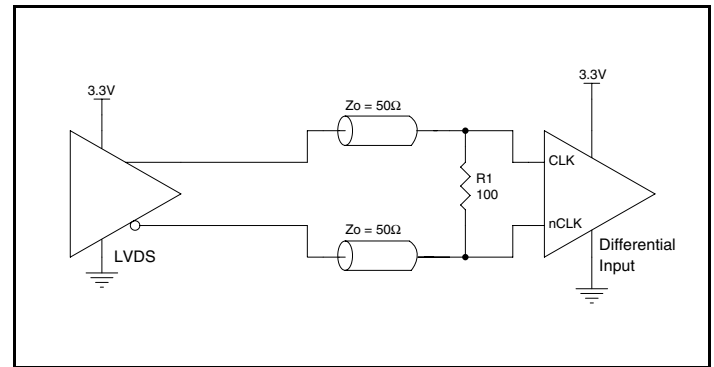


Figure 3D. CLK/nCLK Input Driven by a 3.3V LVDS Driver

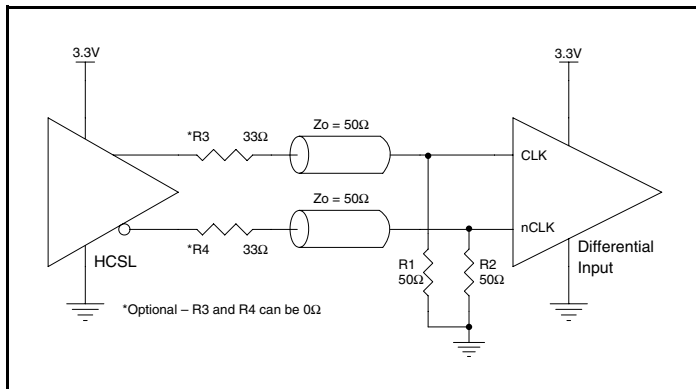


Figure 3E. CLK/nCLK Input Driven by a 3.3V HCSL Driver

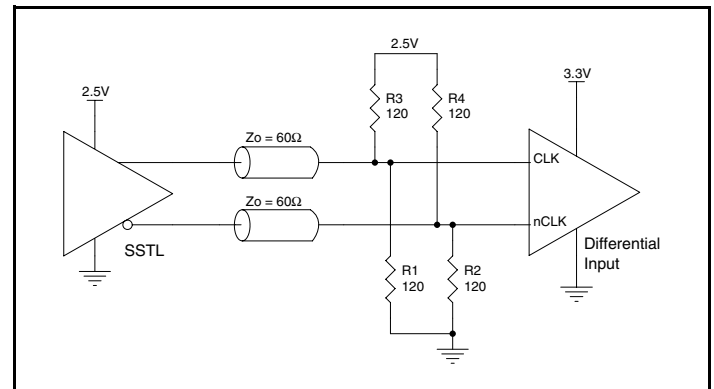


Figure 3F. CLK/nCLK Input Driven by an SSTL Driver

Recommended Termination

Figure 4A is the recommended termination for applications which require the receiver and driver to be on a separate PCB. All traces should be 50Ω impedance.

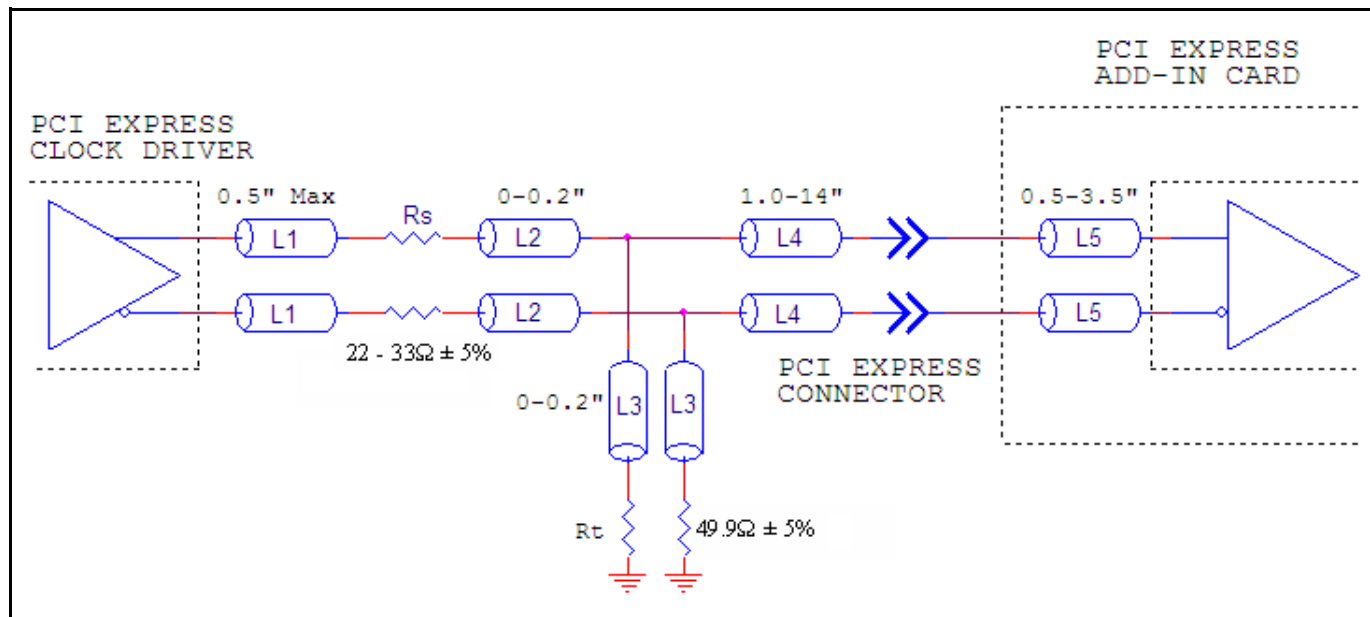


Figure 4A. Recommended Termination

Figure 4B is the recommended termination for applications which require a point to point connection and contain the driver and receiver on the same PCB. All traces should all be 50Ω impedance.

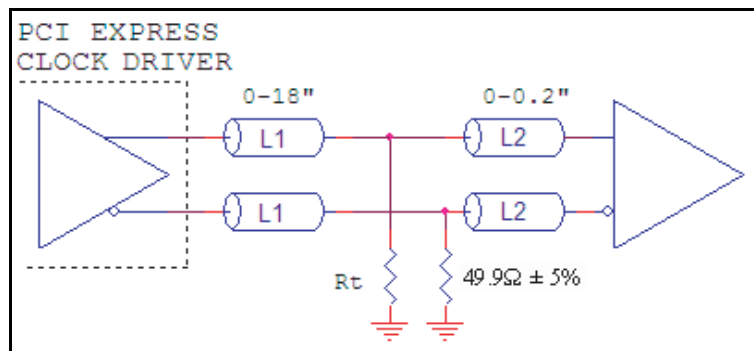


Figure 4B. Recommended Termination

Power Considerations

This section provides information on power dissipation and junction temperature for the ICS851010. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS851010 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{DD} = 3.3V + 5\% = 3.465V$, which gives worst case results.

- Power (core)_{MAX} = $V_{DD_MAX} * I_{DD_MAX} = 3.465V * 105mA = 363.825mW$
- Power (outputs)_{MAX} = **44.5mW/Loaded Output Pair**
If all outputs are loaded, the total power is $10 * 44.5mW = 445mW$

Total Power_{MAX} (3.465V, with all outputs switching) = $363.825mW + 445mW = 808.825mW$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature is 125°C. Limiting the internal transistor junction temperature, T_j , to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming no air flow and a multi-layer board, the appropriate value is 65.7°C/W per Table 4 below.

Therefore, T_j for an ambient temperature of 70°C with all outputs switching is:

$$70^\circ C + 0.809W * 65.7^\circ C/W = 123.2^\circ C. \text{ This is below the limit of } 125^\circ C.$$

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 4. Thermal Resistance θ_{JA} for 32 Lead LQFP, Forced Convection

| θ_{JA} by Velocity | | | |
|---|----------|----------|----------|
| Meters per Second | 0 | 1 | 2.5 |
| Multi-Layer PCB, JEDEC Standard Test Boards | 65.7°C/W | 55.9°C/W | 52.4°C/W |

The purpose of this section is to calculate power dissipation on the IC per HCSL output pair.

HCSL output driver circuit and termination are shown in *Figure 5*.

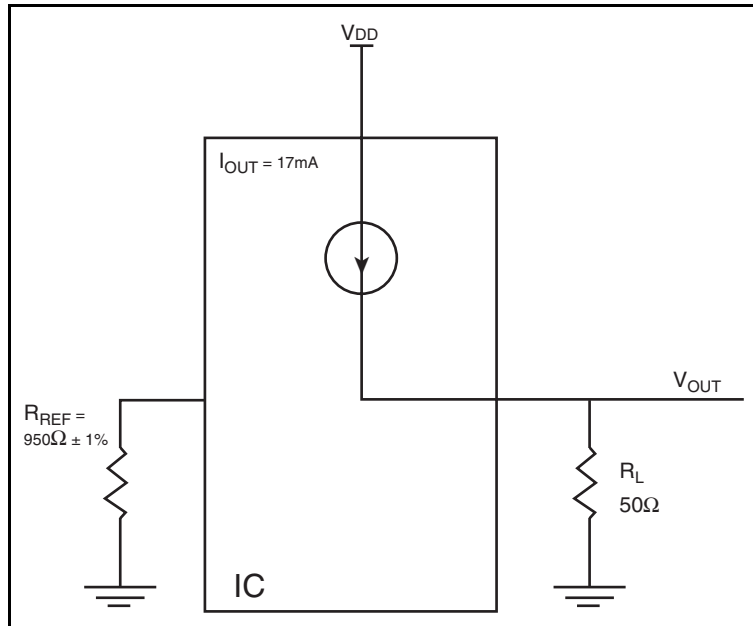


Figure 5. HCSL Driver Circuit and Termination

HCSL is a current steering output which sources a maximum of 17mA of current per output. To calculate worst case on-chip power dissipation, use the following equations which assume a 50Ω load to ground.

The highest power dissipation occurs when V_{DD_MAX} .

$$\text{Power} = (V_{DD_MAX} - V_{OUT}) * I_{OUT},$$

$$\text{since } V_{OUT} = I_{OUT} * R_L$$

$$= (V_{DD_MAX} - I_{OUT} * R_L) * I_{OUT}$$

$$= (3.465\text{V} - 17\text{mA} * 50\Omega) * 17\text{mA}$$

Total Power Dissipation per output pair = **44.5mW**

Reliability Information

Table 5. θ_{JA} vs. Air Flow Table for a 32 Lead LQFP

| θ_{JA} vs. Air Flow | | | |
|---|----------|----------|----------|
| Meters per Second | 0 | 1 | 2.5 |
| Multi-Layer PCB, JEDEC Standard Test Boards | 65.7°C/W | 55.9°C/W | 52.4°C/W |

Transistor Count

The transistor count for ICS851010 is: 843

Package Outline and Package Dimensions

Package Outline - Y Suffix for 32 Lead LQFP

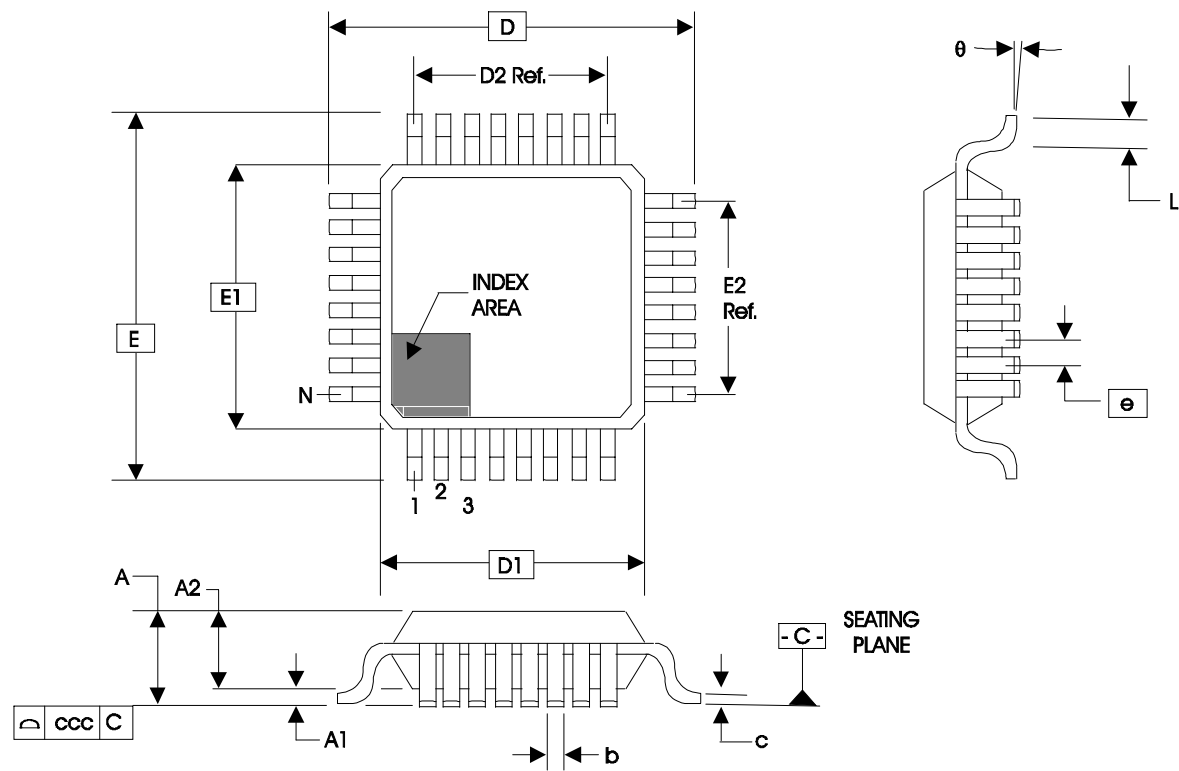


Table 6. Package Dimensions for 32 Lead LQFP

| JEDEC Variation: BBA | | | |
|-------------------------------|------------|---------|---------|
| All Dimensions in Millimeters | | | |
| Symbol | Minimum | Nominal | Maximum |
| N | 32 | | |
| A | | | 1.60 |
| A1 | 0.05 | | 0.15 |
| A2 | 1.35 | 1.40 | 1.45 |
| b | 0.30 | 0.37 | 0.45 |
| c | 0.09 | | 0.20 |
| D & E | 9.00 Basic | | |
| D1 & E1 | 7.00 Basic | | |
| D2 & E2 | 5.60 Ref. | | |
| e | 0.80 Basic | | |
| L | 0.45 | 0.60 | 0.75 |
| θ | 0° | | 7° |
| ccc | | | 0.10 |

Reference Document: JEDEC Publication 95, MS-026

Ordering Information

Table 7. Ordering Information

| Part/Order Number | Marking | Package | Shipping Packaging | Temperature |
|-------------------|--------------|-------------------------|--------------------|-------------|
| 851010AY | ICS851010AY | 32 Lead LQFP | Tray | 0°C to 70°C |
| 851010AYT | ICS851010AY | 32 Lead LQFP | 1000 Tape & Reel | 0°C to 70°C |
| 851010AYLF | ICS851010AYL | Lead-Free, 32 Lead LQFP | Tray | 0°C to 70°C |
| 851010AYLFT | ICS851010AYL | Lead-Free, 32 Lead LQFP | 1000 Tape & Reel | 0°C to 70°C |

NOTE: Parts that are ordered with an “LF” suffix to the part number are the Pb-Free configuration and are RoHS compliant

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Revision History Sheet

| Rev | Table | Page | Description of Change | Date |
|-----|-------|--------|--|--------|
| A | T1 | 2 | Pin Description Table, IREF description corrected 475ohm resistor to 950ohm. | 8/2/10 |
| | | 2 | Corrected <i>Output Driver Current and diagram</i> . | |
| | T3 | 4 | Added note, "Characterized using....". | |
| | | 5 | Added <i>Propagation Delay</i> diagram and corrected <i>HCSL Output Load AC Test Circuit</i> diagram in Parameter Measurement Information section. | |
| | | 7 | Updated <i>Wiring the Differential Input to Accept Single-ended Levels</i> . | |
| | | 10 -11 | Corrected power dissipation calculation and total power dissipation section. Corrected <i>HCSL Driver Circuit Termination</i> diagram. | |
| | | 13 | Updated <i>Package Outline</i> . Converted datasheet format. | |
| | | | | |

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